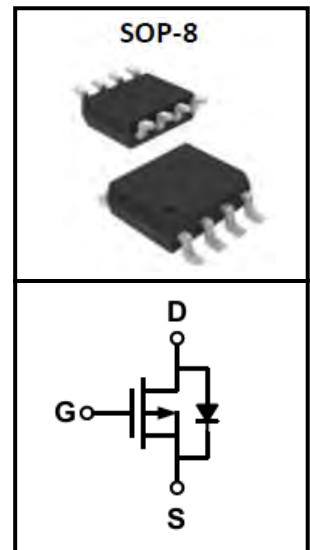


FEATURES

- Super Low Gate Charge
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information

Device	Package	Marking
LM04P021	SOP-8	

Absolute Maximum Ratings at $T_j = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}	-40	V
Continuous Drain Current (note1)	I_D	-8.0	A
Pulsed Drain Current (note2)	I_{DM}	-32	A
Gate Source Voltage	V_{GSS}	± 20	V
Power Dissipation $T_A = 25^\circ\text{C}$ (note4)	P_D	3.5	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient (note1)	$R_{\theta JA}$	42	K/W

Electrical Characteristics $T_j = 25^\circ\text{C}$ unless otherwise specified						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-40	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -40V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	-1	μA
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20V$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.1	-1.7	-2.5	V
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -3A$	--	21	31	$m\Omega$
		$V_{GS} = -10V, I_D = -4A$	--	16	21	$m\Omega$
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = -20V,$ $f = 1.0\text{MHz}$	--	2050	--	pF
Output Capacitance	C_{oss}		--	260	--	
Reverse Transfer Capacitance	C_{rss}		--	150	--	
Total Gate Charge	Q_g	$V_{DD} = -20V, I_D = -8A,$ $V_{GS} = -10V$	--	45	--	nC
Gate-Source Charge	Q_{gs}		--	6	--	
Gate-Drain Charge	Q_{gd}		--	11	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = -20V, R_L = 1.6\Omega$ $V_{GS} = -10V, I_D = -1A$	--	10	--	ns
Turn-on Rise Time	t_r		--	24	--	
Turn-off Delay Time	$t_{d(off)}$		--	40	--	
Turn-off Fall Time	t_f		--	9	--	
Body Diode Characteristics						
Source-Drain Current(Body Diode)	I_{SD}	$T_J = 25^\circ\text{C}$	--	--	-8.0	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = -8A, V_{GS} = 0V$	--	--	-1.2	V

Notes

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The power dissipation is limited by 175°C junction temperature
4. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

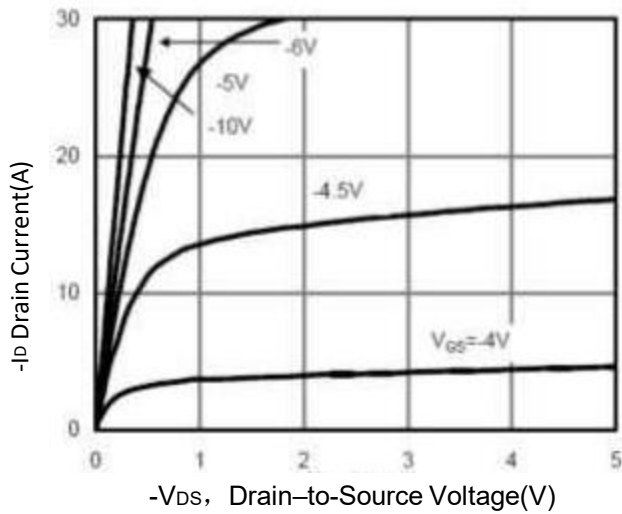


Fig.1 Typical Output Characteristics

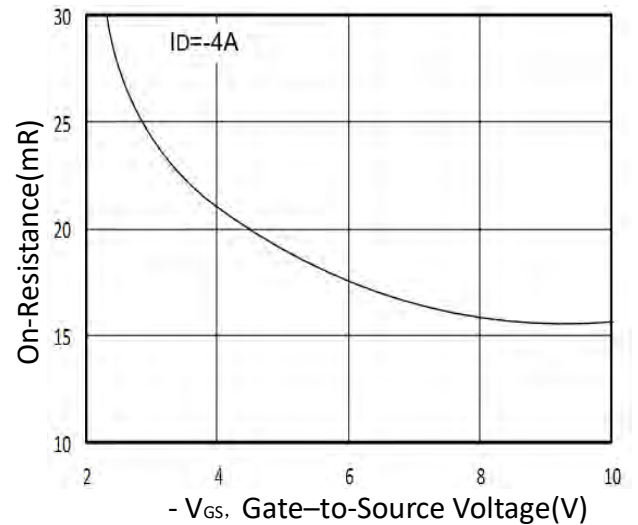


Fig.2 On-Resistance vs. G-S Voltage

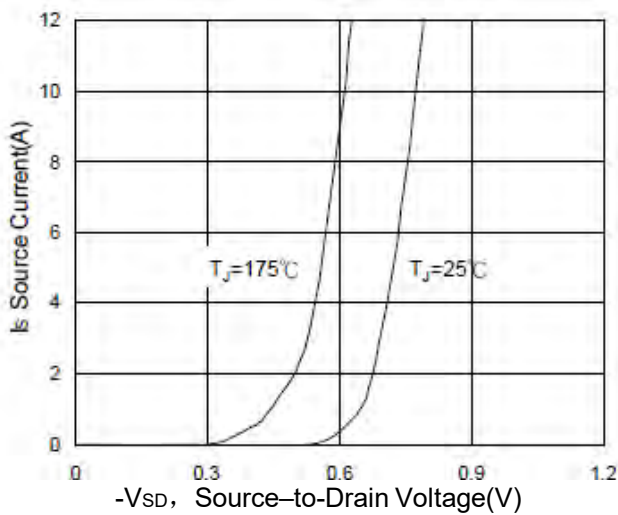


Fig.3 Forward Characteristics of Reverse Diode

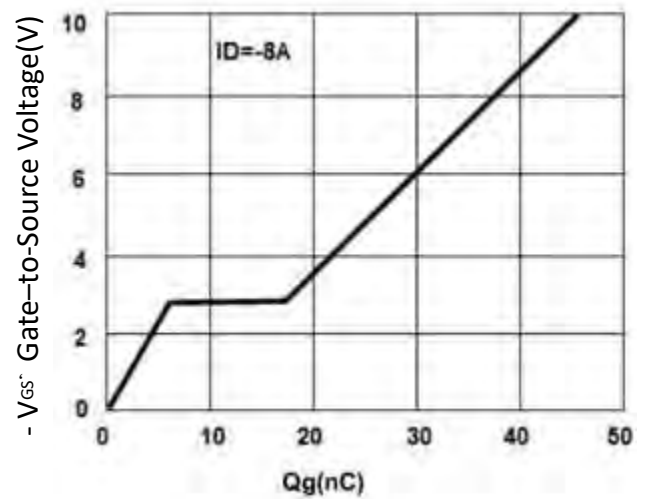


Fig.4 Gate-Charge Characteristics

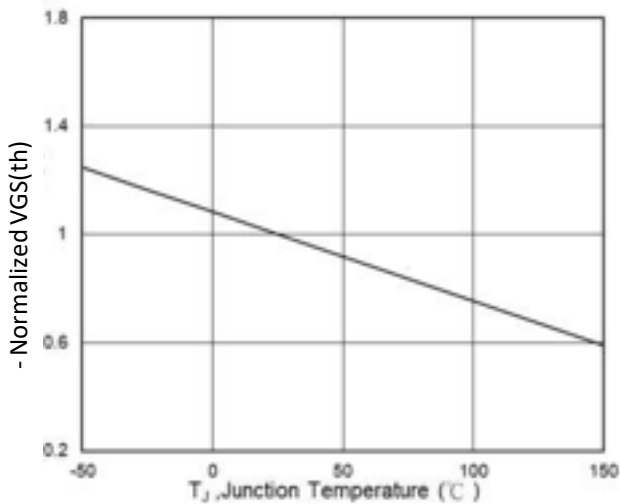


Fig.5 Normalized VGS(th) v.s TJ

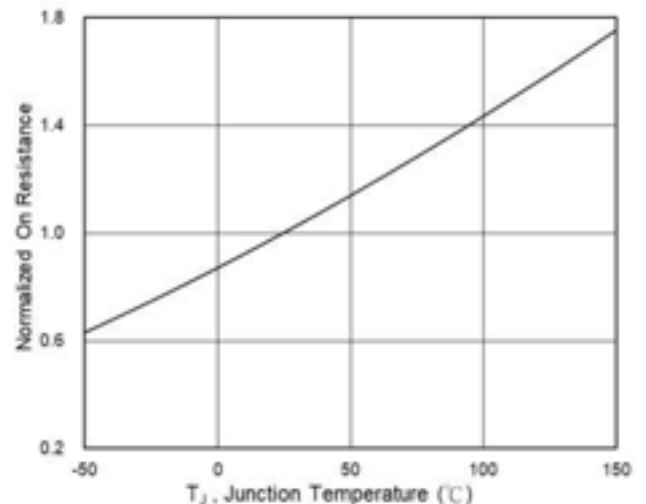


Fig.6 Normalized RDSON v.s TJ

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

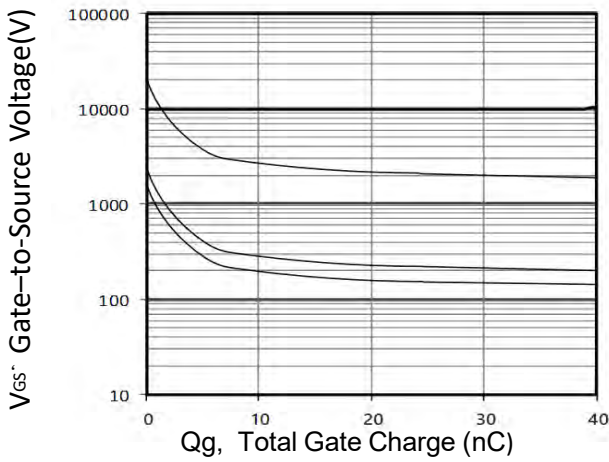


Fig.7 Capacitance

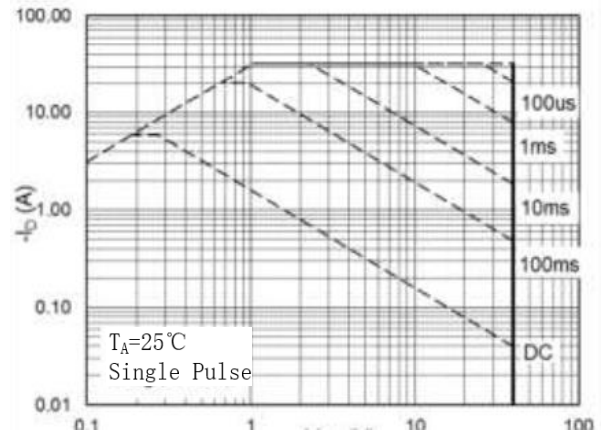


Fig.8 Safe Operating Area

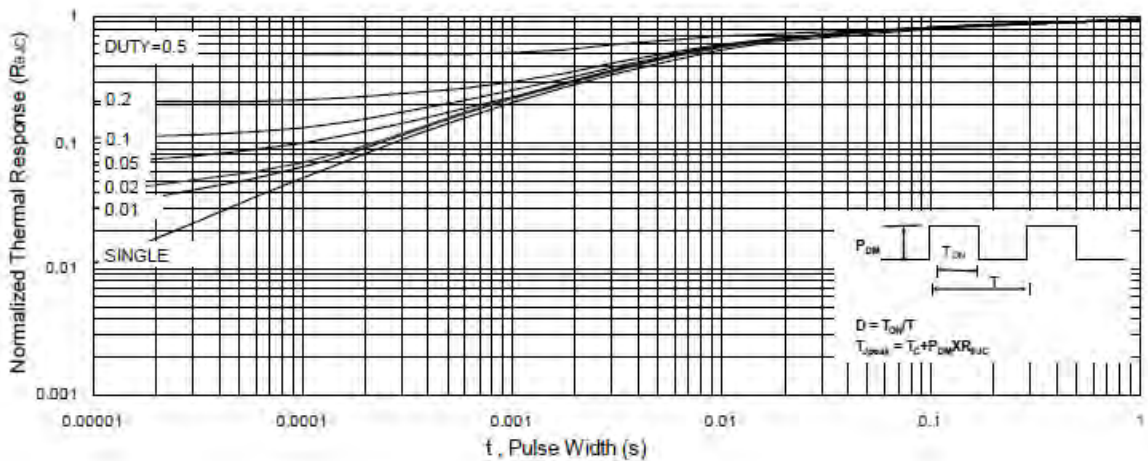


Fig.9 Normalized Maximum Transient Thermal Impedance

Figure A: Gate Charge Test Circuit and Waveform

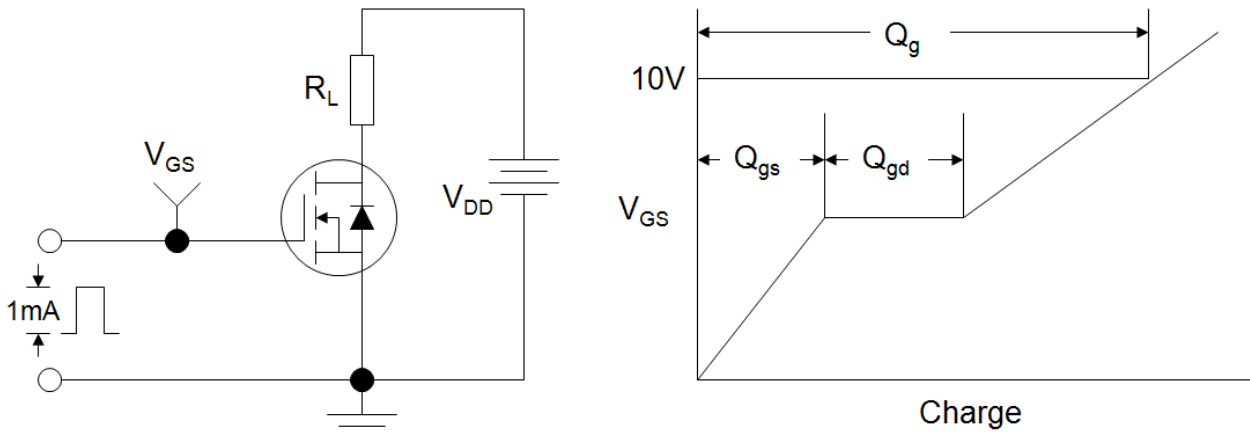


Figure B: Resistive Switching Test Circuit and Waveform

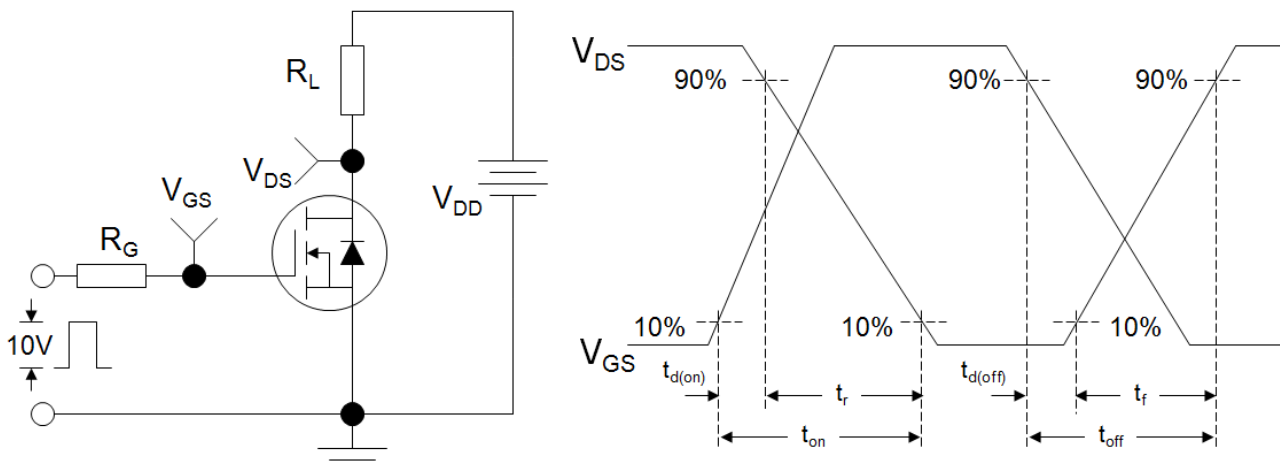
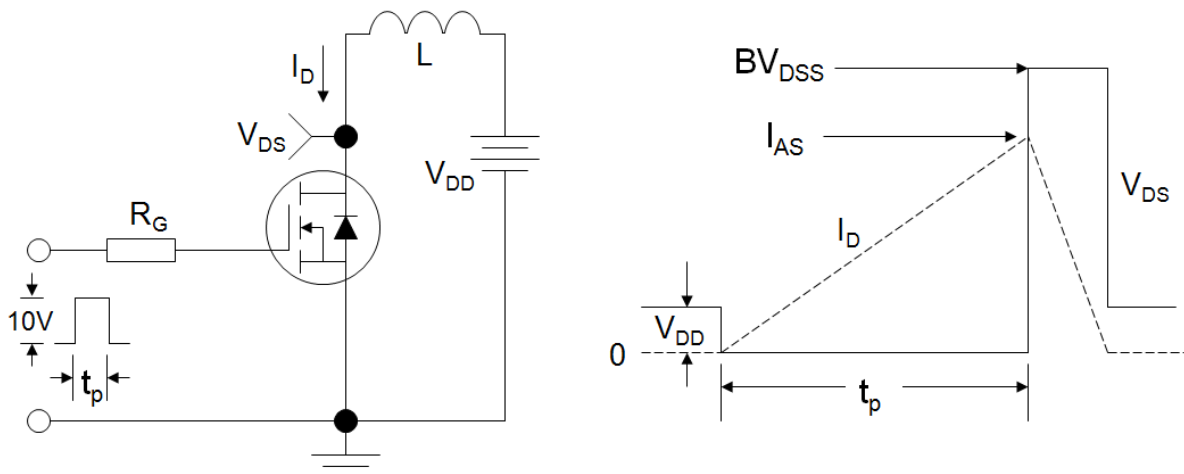
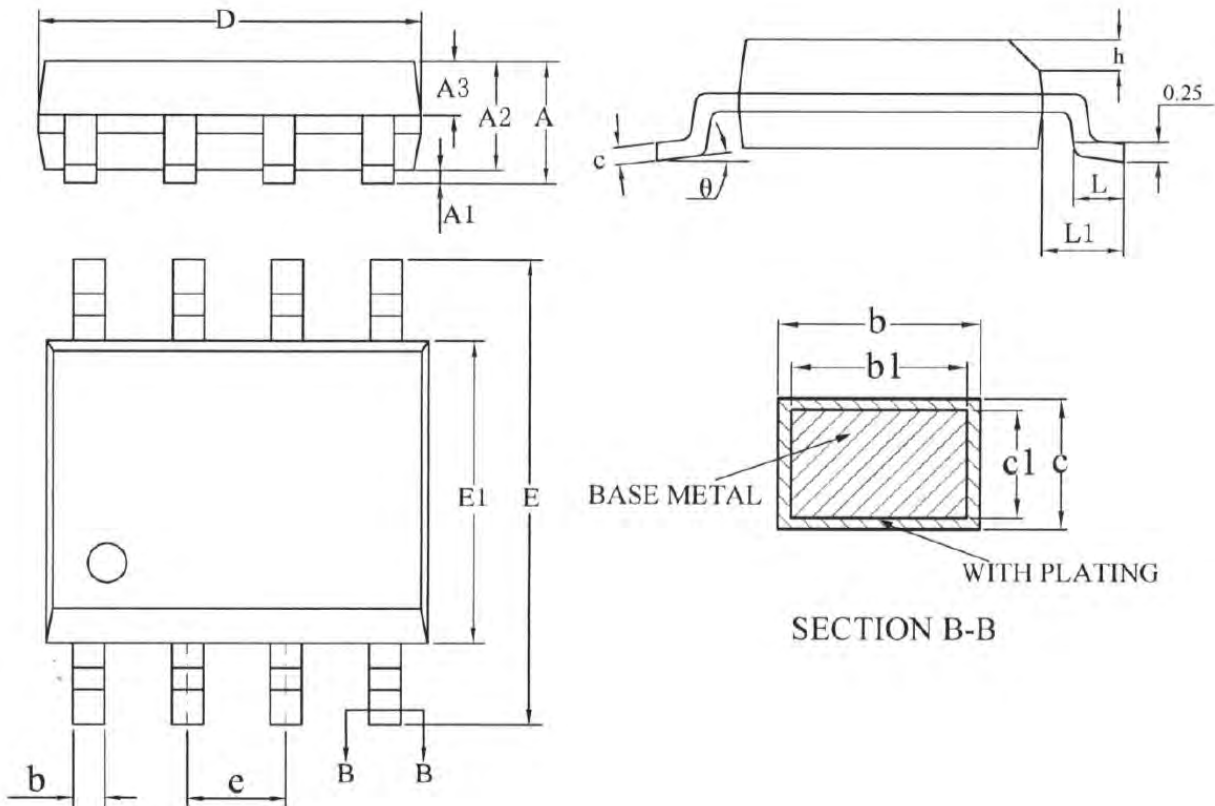


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



SOP-8



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	1.75
A1	0.10	—	0.225
A2	1.30	1.40	1.50
A3	0.60	0.65	0.70
b	0.39	—	0.48
b1	0.38	0.41	0.43
c	0.21	—	0.26
c1	0.19	0.20	0.21

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	4.70	4.90	5.10
E	5.80	6.00	6.20
E1	3.70	3.90	4.10
e	1.27BSC		
h	0.25	—	0.50
L	0.50	—	0.80
L1	1.05BSC		
θ	0	—	8°